

R5590N001A-TR-FE Datasheet



DiGi Electronics Part Number	R5590N001A-TR-FE-DG
Manufacturer	Nisshinbo Micro Devices Inc.
Manufacturer Product Number	R5590N001A-TR-FE
Description	RECTIFIER SWITCH IC FOR BATTERY
Detailed Description	Power Switch/Driver

<https://www.DiGi-Electronics.com>



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

R5590N001A-TR-FE

Series:

*

Base Product Number:

R5590

Manufacturer:

Nisshinbo Micro Devices Inc.

Product Status:

Active

Environmental & Export classification

RoHS Status:

RoHS Compliant

ECCN:

EAR99

Moisture Sensitivity Level (MSL):

1 (Unlimited)

HTSUS:

8542.39.0001

R5590x

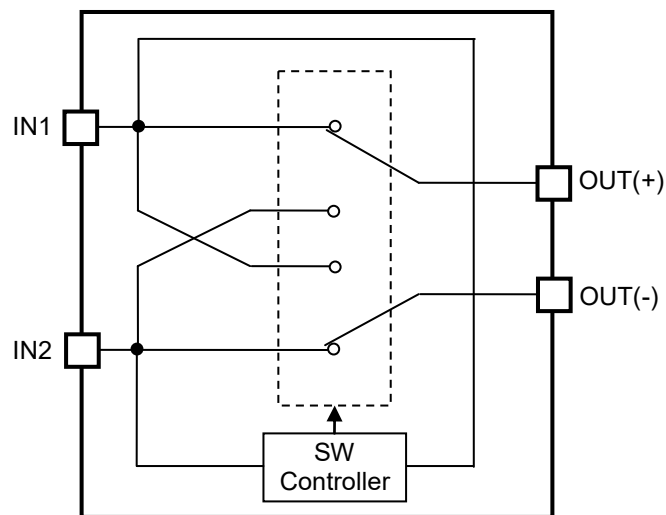
No. EA-320-181214

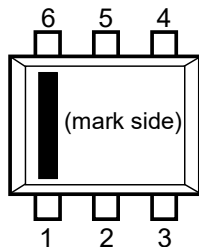
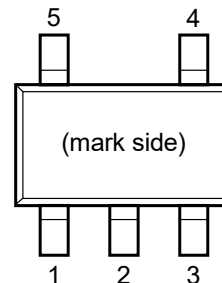
SELECTION GUIDE

The package is a user-selectable option.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
R5590D001A-TR-FE	SON1612-6	4,000 pcs	Yes	Yes
R5590N001A-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes

BLOCK DIAGRAMS**R5590x001A Block Diagram**

PIN DESCRIPTION**SON1612-6 Pin Configuration****SOT-23-5 Pin Configuration****SON1612-6 Pin Description**

Pin No.	Symbol	Description
1	IN2	Input Pin 2
2	OUT (-)	Negative Output Pin ⁽¹⁾
3	NC	No Connection
4	IN1	Input Pin 1
5	OUT (-)	Negative Output Pin ⁽¹⁾
6	OUT (+)	Positive Output Pin

SOT-23-5 Pin Description

Pin No.	Symbol	Description
1	IN1	Input Pin 1
2	OUT (-)	Negative Output Pin
3	NC	No Connection
4	IN2	Input Pin 2
5	OUT (+)	Positive Output Pin

⁽¹⁾ No. 2 pin and No. 5 pin must be wired together at mounting on a board.

R5590x

No. EA-320-181214

ABSOLUTE MAXIMUM RATINGS**Absolute Maximum Ratings**

Symbol	Parameter		Rating	Unit	
ΔV_{IN}	Input Pin Voltage Difference ($ IN1 - IN2 $)		6.0	V	
ΔV_{OUT}	Output Pin Voltage ($OUT(+) - OUT(-)$)		0 to ΔV_{IN}	V	
I_{OUT}	Output Current		400	mA	
P_D	Power Dissipation ⁽²⁾	SON1612-6	Standard Test Land Pattern	500	mW
		SOT-23-5	JEDEC STD.51-7	660	
T_j	Junction Temperature Range		-40 to 125	°C	
T_{stg}	Storage Temperature Range		-55 to 125	°C	

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS**Recommended Operating Conditions**

Symbol	Parameter	Rating	Unit
V_{IN}	Input Voltage	0.9 ~ 5.25	V
T_a	Operating Temperature Range	-40 ~ 85	°C

RECOMMENDED OPERATING CONDITONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽²⁾ Refer to *POWER DISSIPATION* for detailed information.

ELECTRICAL CHARACTERISTICS

The specifications surrounded by are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$.

R5590D001A Electrical Characteristics

(Ta = 25°C)

Symbol	Parameter	Test Conditions/Comments	Min.	Typ.	Max.	Unit	
ΔV_{IN}	Input Pin Voltage Difference		0.9		5.25	V	
R_{ON}	Switch On Resistance	$V_{IN} = 1\text{ V}, I_{OUT} = 100\text{ mA}$		0.65	1.40	Ω	
		$V_{IN} = 1.5\text{ V}, I_{OUT} = 100\text{ mA}$		0.40	0.85		
		$V_{IN} = 5.25\text{ V}, I_{OUT} = 100\text{ mA}$		0.30	0.62		
I_{SS}	Supply Current	$V_{IN} = 1.5\text{ V}, I_{OUT} = 0\text{ mA}$	$T_a = 25^{\circ}\text{C}$		0.05	μA	
		$V_{IN} = 5.25\text{ V}, I_{OUT} = 0\text{ mA}$	$T_a = 25^{\circ}\text{C}$		0.15		4.5
			$-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$				55

All parameters listed under *ELECTRICAL CHARACTERISTICS* are done under the pulse load condition ($T_J \approx T_a = 25^{\circ}\text{C}$).

R5590N001A Electrical Characteristics

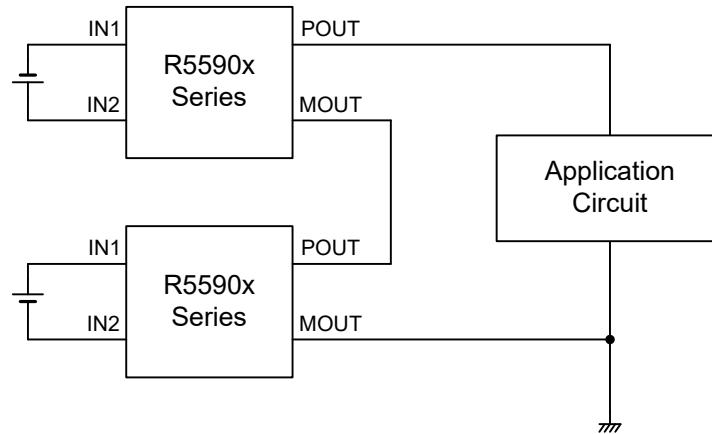
(Ta = 25°C)

Symbol	Parameter	Test Conditions/Comments	Min.	Typ.	Max.	Unit	
ΔV_{IN}	Input Pin Voltage Difference		0.9		5.25	V	
R_{ON}	Switch On Resistance	$V_{IN} = 1\text{ V}, I_{OUT} = 100\text{ mA}$		0.75	1.45	Ω	
		$V_{IN} = 1.5\text{ V}, I_{OUT} = 100\text{ mA}$		0.50	0.88		
		$V_{IN} = 5.25\text{ V}, I_{OUT} = 100\text{ mA}$		0.35	0.65		
I_{SS}	Supply Current	$V_{IN} = 1.5\text{ V}, I_{OUT} = 0\text{ mA}$	$T_a = 25^{\circ}\text{C}$		0.05	μA	
		$V_{IN} = 5.25\text{ V}, I_{OUT} = 0\text{ mA}$	$T_a = 25^{\circ}\text{C}$		0.15		4.5
			$-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$				55

All test items listed under *ELECTRICAL CHARACTERISTICS* are done under the pulse load condition ($T_J \approx T_a = 25^{\circ}\text{C}$).

R5590x

No. EA-320-181214

APPLICATION INFORMATION**Typical Rectification Circuit with 2 Serial Batteries****TECHNICAL NOTES**

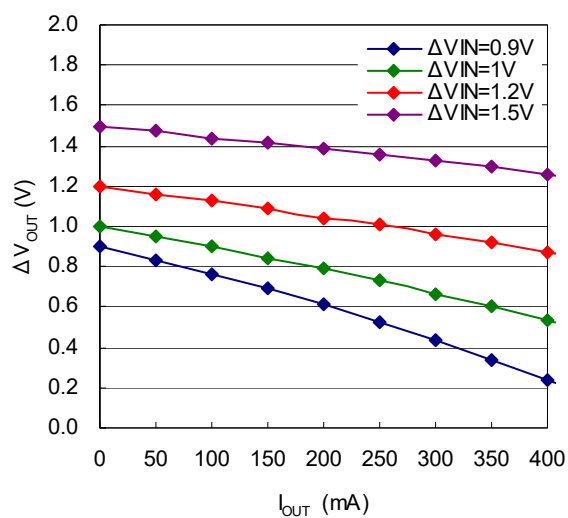
If the input voltage difference becomes less than output voltage difference, which could happen when the AC power source is rectified or the DC power source having different voltage is used in parallel, the current flows from the output side to the input side. To prevent this, use a reverse current prevention diode.

The short circuit current flows when the output pin is shorted while bias voltage is applied to the input pin. The R5590x should be operated within the absolute maximum ratings of each package.

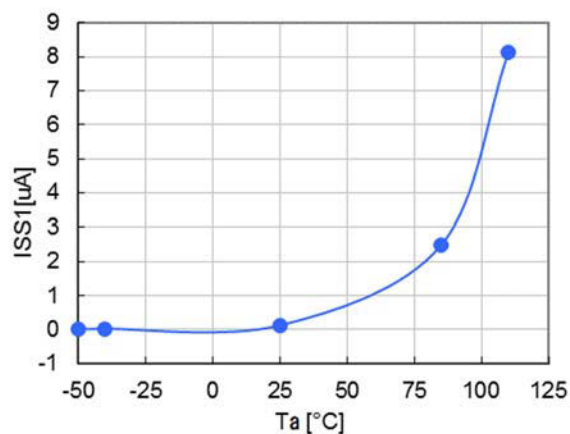
TYPICAL CHARACTERISTICS

Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

1. Output Current vs. Output Pin Voltage ($T_a = 85^\circ\text{C}$)



2. Operating Temperature vs. Supply Current ($I_{N1}=5.25V$)



POWER DISSIPATION**SON1612-6**

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

Item	Standard Test Land Pattern
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50% Bottom Side: Approx. 50%
Through-holes	φ 0.5 mm × 24 pcs

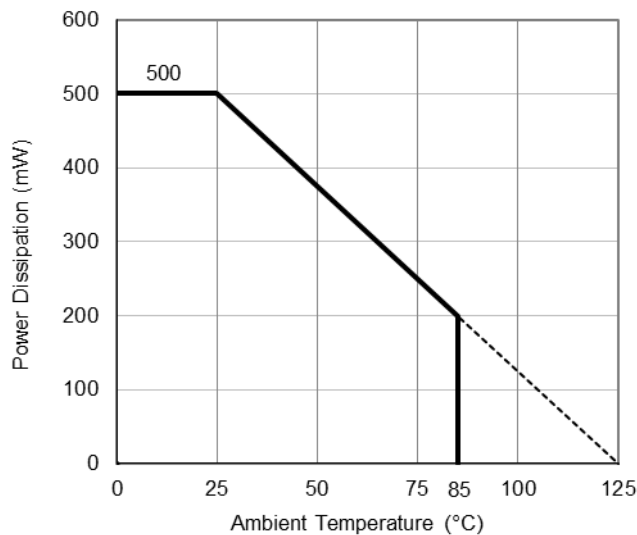
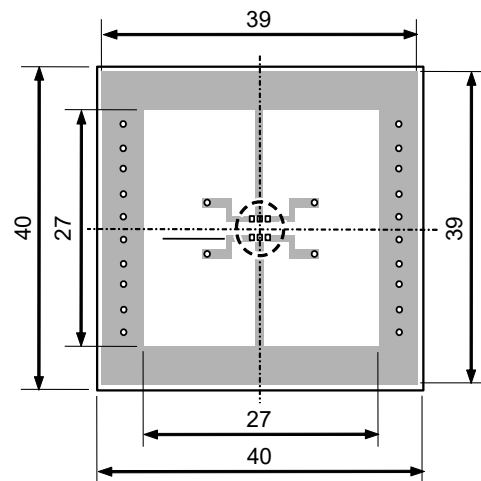
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

Item	Standard Test Land Pattern
Power Dissipation	500 mW
Thermal Resistance (θ_{ja})	$\theta_{ja} = 200^{\circ}\text{C/W}$
Thermal Characterization Parameter (ψ_{jt})	$\psi_{jt} = 82^{\circ}\text{C/W}$

θ_{ja} : Junction-to-Ambient Thermal Resistance

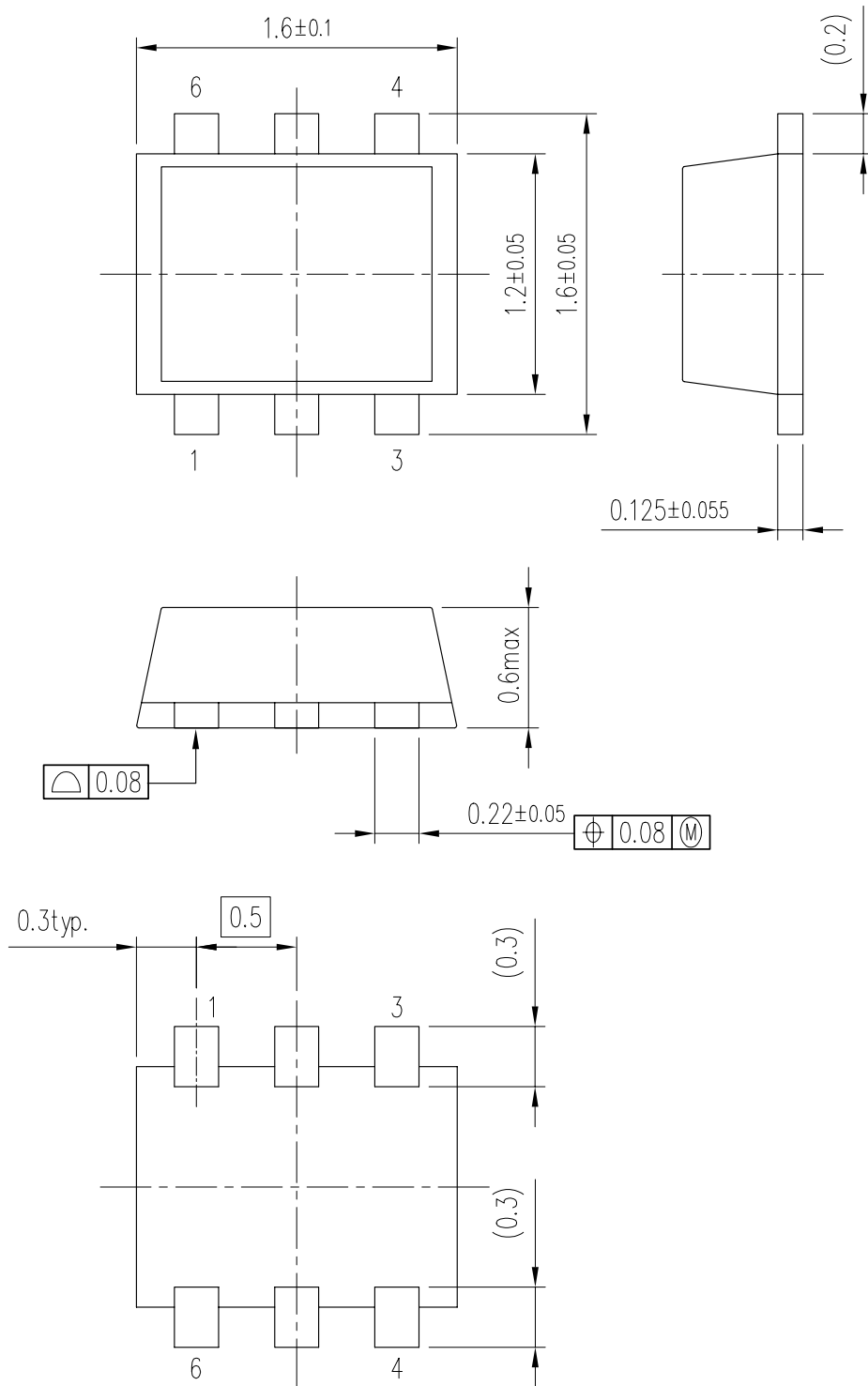
ψ_{jt} : Junction-to-Top Thermal Characterization Parameter

**Power Dissipation vs. Ambient Temperature****Measurement Board Pattern**

PACKAGE DIMENSIONS

SON1612-6

Ver. A



UNIT: mm

SON1612-6 Package Dimensions

POWER DISSIPATION**SOT-23-5**

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 7 pcs

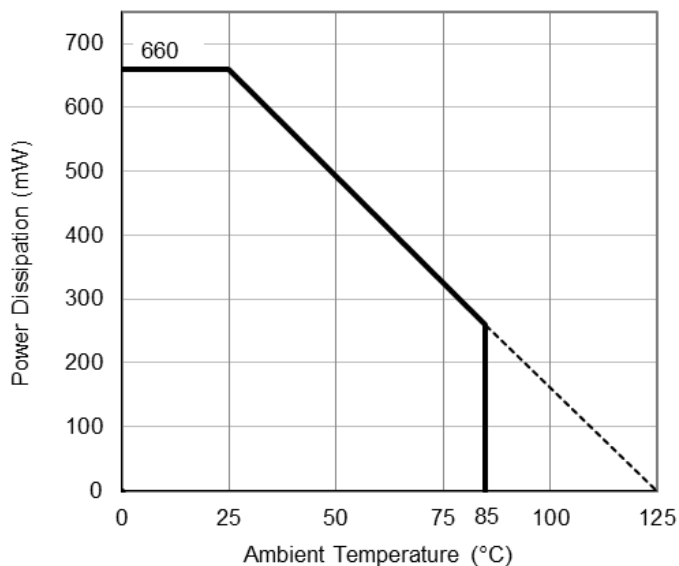
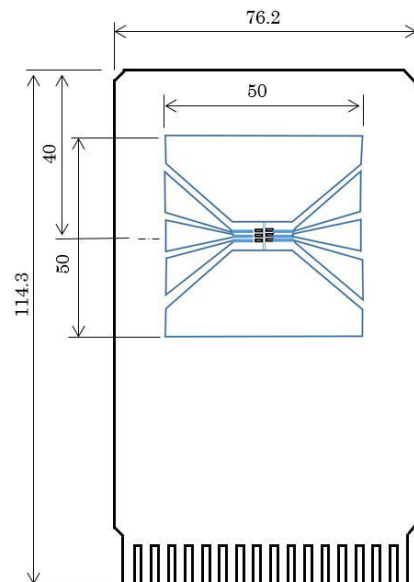
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θ_{ja})	$\theta_{ja} = 150^{\circ}\text{C/W}$
Thermal Characterization Parameter (ψ_{jt})	$\psi_{jt} = 51^{\circ}\text{C/W}$

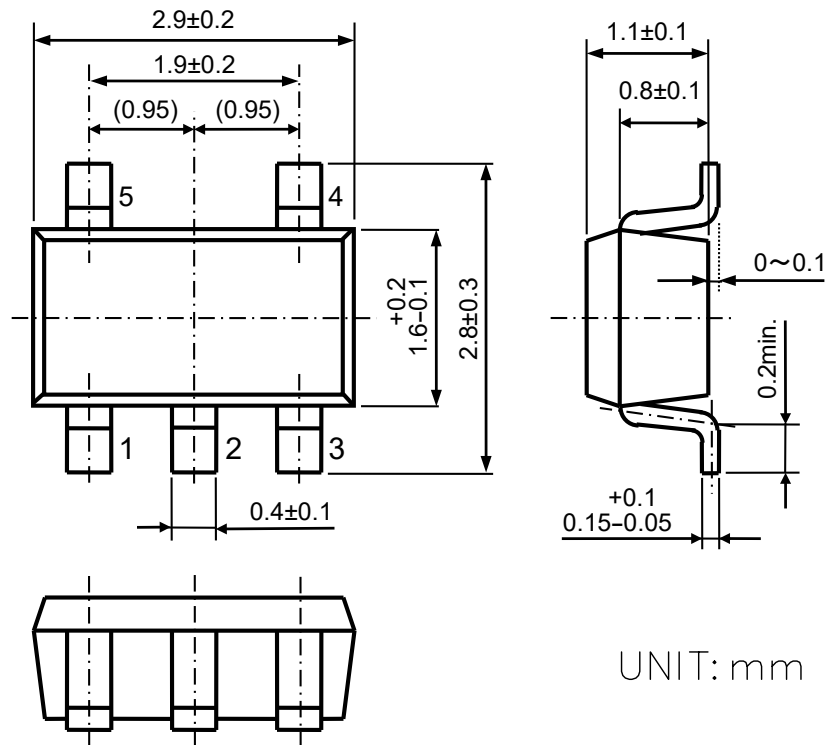
θ_{ja} : Junction-to-Ambient Thermal Resistance

ψ_{jt} : Junction-to-Top Thermal Characterization Parameter

**Power Dissipation vs. Ambient Temperature****Measurement Board Pattern**

PACKAGE DIMENSIONS**SOT-23-5**

Ver. A

**SOT-23-5 Package Dimensions**



1. The products and the product specifications described in this document are subject to change or discontinuation of production without notice for reasons such as improvement. Therefore, before deciding to use the products, please refer to our sales representatives for the latest information thereon.
2. The materials in this document may not be copied or otherwise reproduced in whole or in part without prior written consent of our company.
3. Please be sure to take any necessary formalities under relevant laws or regulations before exporting or otherwise taking out of your country the products or the technical information described herein.
4. The technical information described in this document shows typical characteristics of and example application circuits for the products. The release of such information is not to be construed as a warranty of or a grant of license under our company's or any third party's intellectual property rights or any other rights.
5. The products listed in this document are intended and designed for use as general electronic components in standard applications (office equipment, telecommunication equipment, measuring instruments, consumer electronic products, amusement equipment etc.). Those customers intending to use a product in an application requiring extreme quality and reliability, for example, in a highly specific application where the failure or misoperation of the product could result in human injury or death (aircraft, spacevehicle, nuclear reactor control system, traffic control system, automotive and transportation equipment, combustion equipment, safety devices, life support system etc.) should first contact us.
6. We are making our continuous effort to improve the quality and reliability of our products, but semiconductor products are likely to fail with certain probability. In order to prevent any injury to persons or damages to property resulting from such failure, customers should be careful enough to incorporate safety measures in their design, such as redundancy feature, fire containment feature and fail-safe feature. We do not assume any liability or responsibility for any loss or damage arising from misuse or inappropriate use of the products.
7. Anti-radiation design is not implemented in the products described in this document.
8. The X-ray exposure can influence functions and characteristics of the products. Confirm the product functions and characteristics in the evaluation stage.
9. WLCSP products should be used in light shielded environments. The light exposure can influence functions and characteristics of the products under operation or storage.
10. There can be variation in the marking when different AOI (Automated Optical Inspection) equipment is used. In the case of recognizing the marking characteristic with AOI, please contact our sales or our distributor before attempting to use AOI.
11. Please contact our sales representatives should you have any questions or comments concerning the products or the technical information.



Nisshinbo Micro Devices Inc.

Official website

<https://www.nisshinbo-microdevices.co.jp/en/>

Purchase information

<https://www.nisshinbo-microdevices.co.jp/en/buy/>

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.